

**A SEMICONDUCTOR DEVICE HAVING A FUSE AND METHOD OF
FORMING THEREOF**

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Abstract of the Disclosure

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A fuse (43) is formed overlying a passivation layer (35) and under a packaging material (55, 70). In one embodiment, a fuse (43) is blown before the packaging material (55, 70) is formed. In some embodiments, the fuse (43) may be formed of metal (47), a metal nitride (42) or a combination thereof.